

PATENT  
Atty. Dkt. No. APPM/4215Y1/CMP/CMP/RKK

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Sun et al.

Serial No.: 09/645,690

Filed: August 24, 2000

For: CU CMP POLISHING PAD  
CLEANING§§ Group Art Unit: 1746  
§§  
§§ Examiner: Alexander Markoff  
§§  
§§ Confirmation No.: 4428MAIL STOP: AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>9/30/2005</u> with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<u>9/30/2005</u> Date	<u>[Signature]</u> Signature

DECLARATION UNDER 37 C.F.R. § 1.131

The undersigned inventor, Lizhong Sun, hereby declare as follows:

1. That I am a co-inventor of the above referenced patent application.
2. Attached is an invention alert (Exhibit A) dated prior to August 7, 2000, disclosing improvement of cleaning a CMP polishing pad by using a pad cleaning composition. All masked dates in Exhibit A are prior to August 7, 2000. Confidential information not relevant to the invention date of the present application is also masked.
3. That Exhibit A describes a method for cleaning a polishing pad surface subsequent to CMP a wafer surface containing copper or a copper-based alloy using a pad cleaning composition and the method was conceived prior to August 7, 2000.
4. In view of Exhibit A and the above statements, the invention of pending claims 1-18, 26-31 and 33 was conceived prior to August 7, 2000, and filed with due diligence prior to August 7, 2000, to the filing of the patent application on August 24, 2000.

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5. The undersigned, Lizhong Sun, hereby declares that all statements made herein of my own knowledge are true and that these statements made on information and belief are believed to be true and further that these statements were made with knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of this application or any patent resulting therefrom.

09/27/05

Date

L. Y. S.

Lizhong Sun